

CLAIMS

What is claimed is:

1. A digital image capturing module assembly, which comprises:

a lens holder, which has one side defined as a focusing plane, and which is formed with a plurality of aligning posts on the periphery of the focusing plane and is further formed with a ring plane between the focusing plane and the aligning posts that completely surrounds the focusing plane;

an adhesive layer, which is coated over the periphery of the focusing plane and over the ring plane; and

a photosensitive printed circuit board, which is formed with a plurality of aligning holes corresponding to the aligning posts on the lens holder, and which is mounted on the lens holder by fitting the aligning holes thereof to the aligning posts on the lens holder;

wherein

the respective tips of the aligning posts on the lens holder are each melted into a bolting structure to secure the photosensitive printed circuit board firmly in position on the lens holder;

and wherein

the firmly-secured photosensitive printed circuit board forcefully presses against the adhesive layer to be thereby adhered firmly in position on the lens holder with the adhesive layer providing a sealed light-impenetrable effect at the junction between the photosensitive printed circuit board and the lens holder.

2. The digital image capturing module assembly of claim 1, wherein the photosensitive printed circuit board is a CCD-based photosensitive printed circuit board.
3. The digital image capturing module assembly of claim 1, wherein the photosensitive printed circuit board is a CMOS-based photosensitive printed circuit board.
4. The digital image capturing module assembly of claim 1, wherein the aligning posts on the lens holder are made of plastics.
5. A method for fabricating a digital image capturing module, comprising:
 - preparing a lens holder, which has one side defined as a focusing plane, and which is formed with a plurality of aligning posts on the periphery of the focusing plane and is further formed with a ring plane between the focusing plane and the aligning posts that completely surrounds the focusing plane;
 - preparing a photosensitive printed circuit board which is formed with a plurality of aligning holes corresponding to the aligning posts on the lens holder;
 - coating an adhesive layer over the periphery of the focusing plane and over the ring plane; and;
 - mounting the photosensitive printed circuit board in position on the lens holder by fitting the aligning holes in the photosensitive printed circuit board to the aligning posts on the lens holder; and
 - melting the respective tips of the aligning posts on the lens holder so as to transform the respective tips of the aligning posts into a bolting structure to secure the photosensitive printed circuit board in position on the lens holder as well as to allow the

photosensitive printed circuit board to forcefully press against the adhesive layer to allow the photosensitive printed circuit board to be adhered firmly in position on the lens holder with the adhesive layer providing a sealed light-impenetrable effect at the junction between the photosensitive printed circuit board and the lens holder.

6. The method of claim 5, wherein the photosensitive printed circuit board is a CCD-based photosensitive printed circuit board.

7. The method of claim 5, wherein the photosensitive printed circuit board is a CMOS-based photosensitive printed circuit board.

8. The method of claim 5, wherein the aligning posts on the lens holder are made of plastics.

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